| ABSOCIATION CONNECTING ELECTRONICS INDUSTRIES® INCLUSTRIES® | ckburn, Illinois. A | All rights reserved un ntions. | nder both | This docume level parts, t | ent is a declara he declaration | tion of the s encompasse | ubstances es all lowe | within the manufacture or level materials for w | rer listed i | tem. Note: i nanufacture | f the item is an as r has engineering | sembly with lower responsibility. | |
|--|---|--------------------------------|-------------------------|-------------------------------|---|---|--------------------------|--|------------------|-----------------------------|--|-----------------------------------|--|
| | IPC Web Site for Information on IPC-1752 Standard Form Ty http://www.ipc.org/IPC-175x Distribu | | | | Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Material | | | | ials and M | ls and Mfg Information | | | |
| Supplier Information | | | | | | | | | | | | | |
| Company name* Company unique ID | | | Unique | | | ique ID Authority | | | Respon | Response Date* | | | |
| onsemi | ai | | | | | | | | 2023-06-08 | | | | |
| Contact Name | t Name Title - Contact | | | | Phone - Contact* | | | | Email - Contact* | | | | |
| duct-Env-Stewards Product Enviro Compliance | | | | NA | | | | Product-Env-Stewards@onsemi.com | | | | | |
| uthorized Representative* Title - Representative | | | Phone - Representative* | | | | Email - Representative* | | | | | | |
| Product-Env-Stewards Product Enviro Compliance | | | | NA | | | | Product-Env-Stewards@onsemi.com | | | | | |
| Requester Item Number Mfr | tem Number | Mfr Item Name | | | Effective Dat | e Version | | Manufacturing Site | | Weight* | UOM | Unit Type | |
| MCI | MC100EP446FAG BBG ECL PAR | | LLEL T/SERIA | EL T/SERIAL 2 | | | | TW2 | | 175.1 | mg | Each | |
| Manufacturing Proccess Information | | | | | | | | | | | | | |
| Terminal Plating / Grid Array Material | lating / Grid Array Material Terminal Base Alloy | | -STD-020 MSL | L Rating Peak | | Process Body Temperature Max Time at Peak | | Temperature Number of Reflow Cycles | | cles | | | |
| Matte Tin (Sn) - annealed CU Alloy 2 | | | 2 | | 260 | | С | 30 | secor | nds 3 | | | |
| Comments | | | | | | | | | | | | | |
| ATTENTION: MSL 2 Rated item requires Dry Pac | k (after electrica | l test) | | | | | | | | | | | |
| For more information regarding material composit | on please refer to | o page 3 | | | | | | | | | | | |

| RoHS Material Composition Declaration | | | | Declaration Type * | Detailed | | | | | |
|--|--|--|---|---|---|--|--|--|--|--|
| Directive 2015/863/EU amending RoHS Directive 2011/65/EU | (Pb), Mercury (Hg), Hexavalent Chror | efinition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead ercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl e (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP). | | | | | | | | |
| cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a | ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe y others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the | henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies | RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and cc for issues that arise regarding inform | ce of its products with European Union membe | ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of | | | | | |
| RoHS Declaration * 1 - Item(s) | does not contain RoHS restricted substa | ances per the definitio | on above | Supplier Acceptance | * Accepted | | | | | |
| Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions. | | | | | | | | | | |
| Exemption List Version | EL-2011/534/EU | | | | | | | | | |
| Declaration Signature | | | | | | | | | | |
| Instructions: Complete all of the required fin Requester) and click on Submit Form to have | elds on all pages of this form. Select the form returned to the Requester | he "Accepted" on th | e Supplier Acceptance drop-down | . This will display the signature area. Digital | lly sign the declaration (if required by the | | | | | |
| Supplier Digital Signature Ra | stislav Drska | Le | | | | | | | | |

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

| Homogeneous Material | Weight | Unit of Measure | Level | Substance | CAS | Exempt | Weight | Unit of Measure |
|----------------------|--------|-----------------|----------|---------------------|------------------|--------|----------|-----------------|
| Die | 0.33 | mg | Supplier | Silicon (Si) | 7440-21-3 | | 0.33 | mg |
| Die Attach 3.19 | 3.19 | mg | Supplier | Silver (Ag) | 7440-22-4 | | 2.3925 | mg |
| | | | Supplier | Epoxy resins | 129915-35-1 | | 0.7975 | mg |
| Lead Frame 49.99 | 49.99 | mg | Supplier | Silver (Ag) | 7440-22-4 | | 0.15 | mg |
| | | | Supplier | Magnesium (Mg) | 7439-95-4 | | 0.05 | mg |
| | | | Supplier | Silicon (Si) | 7440-21-3 | | 0.3499 | mg |
| | | | В | Nickel (Ni) | 7440-02-0 | | 1.4997 | mg |
| | | | Supplier | Copper (Cu) | 7440-50-8 | | 47.9404 | mg |
| Mold Compound-Black | 114.24 | mg | | Epoxy Phenol Resin | proprietary data | | 11.9952 | mg |
| | | | Supplier | Fused Silica (SiO2) | 60676-86-0 | | 102.2448 | mg |
| Plating | 6.7 | mg | Supplier | Tin (Sn) | 7440-31-5 | | 6.7 | mg |
| Wire Bond - Au | 0.65 | mg | Supplier | Gold (Au) | 7440-57-5 | | 0.65 | mg |